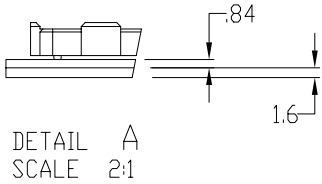
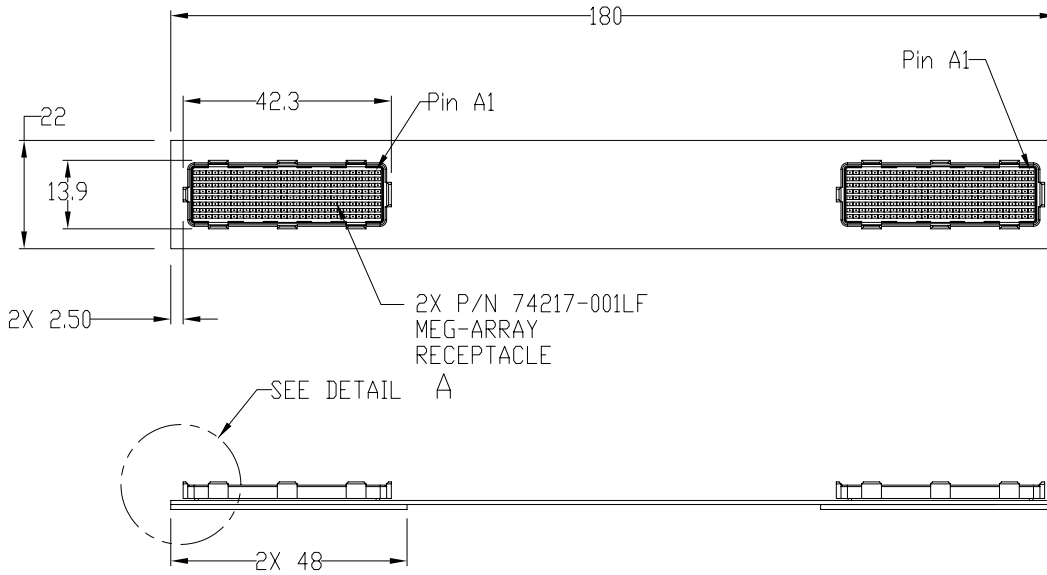


PRODUCT NUMBER
10061262-001LF



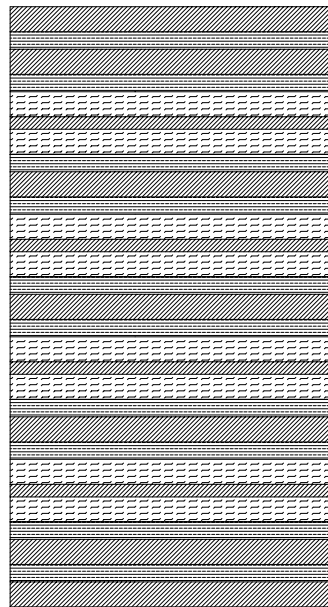
mat'l. code		surface		tolerance		projection		product family	
SEE NOTES		ASME Y14.5		ASME Y14.5		MM		title	
ltr	ecm no	dr	date	tolerances unless otherwise specified		scale 1:1		FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES	
A	v06-0065	DAI	01/25/06	angle	.X ±.3	FCI		dwg no	sheet 1 of 2
B	v06-0112	DAI	02/06/06	□	.XX ±.10	scale 1:1		10061262	A4
C	v07-0276	DAI	2007-04-05	0° ±2'	.XXX ±.050			type	CUSTOMER Drawing
				dr	D.INGRAM	01/25/06			
				engr	D.BRANN	01/25/06			
				chr	D.BRANN	01/25/06			
				appd	D.BRANN	01/25/06			
sheet index	revision sheet	c	c						
	1	2							

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NOTES:

1. MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY
CONTACT PLATING: 38µm (15µ in) Au OVER Ni
SOLDER BALL PLATING: SnAgCu
BACKER BOARD: G-10
FLEX CIRCUIT: Polyimide
2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHEMENT.
3. LEAD FREE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
4. FOR PROPER APPLICATION, FOLLOW FCI APPLICATION SPECIFICATION GS-20-033.
5. CONSTRUCTION PER IPC-6013 CLASS II TYPE 3 DR 4.
6. MEG-ARRAY PRODUCT SPECIFICATION: GS-12-100.

Cover coat
½ OZ Copper
Adhesive
Polyimide



.81/.84

mat'l. code		surface		tolerance		projection		product family	
SEE NOTES		ASME Y14.5		ASME Y14.5					
ltr	ecm no	dr	date	tolerances unless otherwise specified		MM		title	
c				angle	.X ±.3	←		FLEX CIRCUIT W/240 POS. MEG-ARRAY	
				dr	.XX ±.10	scale 1:1		RECEPTACLE ASSEMBLIES	
				or ±2'	.XXX ±.050			dwg no	
				dr	D.INGRAM 01/25/06			sheet 2 of	
				engr	D.BRANN 01/25/06			10061262	
				chr	D.BRANN 01/25/06			A4	
				appd	D.BRANN 01/25/06			type	
								CUSTOMER Drawing	
sheet index	revision sheet								